

## **General Description**

The NTMFS4C08N use advanced SGT MOSFET

technology to provide low RDS(ON), low gate charge,

fast switching and excellent avalanche characteristics.

This device is specially designed to get better ruggedness

and suitable to use in

#### **General Features**

V<sub>DS</sub> =30V l<sub>D</sub> =60A

 $R_{DS(ON)} < 5.8 m\Omega @ V_{GS} = 10V$ 

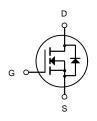
## **Applications**

Consumer electronic power supply Motor control

Synchronous-rectification Isolated DC

Synchronous-rectification applications

DFN5X6-8L



N-Channel MOSFET

### **Package Marking and Ordering Information**

Product ID	Pack	Brand	Qty(PCS)
NTMFS4C08N	DFN5X6-8L	HXY MOSFET	5000

#### Absolute Maximum Ratings (T<sub>c</sub>=25<sup>o</sup>C unless otherwise noted)

Symbol	Parameter	Rating	Units		
V <sub>DS</sub>	Drain-Source Voltage	Drain-Source Voltage 30			
Vgs	Gate-Source Voltage	±20	V		
I <sub>D</sub> @T <sub>C</sub> =25°C	Continuous Drain Current, Ves @ 10V 60		А		
I <sub>D</sub> @T <sub>C</sub> =100°C	Continuous Drain Current, V <sub>GS</sub> @ 10V	38	А		
Ірм	Pulsed Drain Current <sup>2</sup>	135	А		
EAS	Single Pulse Avalanche Energy <sup>3</sup>	29.8	mJ		
P <sub>D</sub> @T <sub>C</sub> =25°C	Total Power Dissipation⁴	30	W		
Тѕтс	Storage Temperature Range -55 to 150		°C		
TJ	Operating Junction Temperature Range	-55 to 150	°C		
R <sub>θ</sub> JC	Thermal Resistance from Junction-to-Ambient <sup>3</sup> 4.6		°C/W		
Reja	Thermal Resistance Junction-Ambient <sup>1</sup>	50	°C/W		



## Electrical Characteristics (T<sub>J</sub> = 25°C, unless otherwise noted)

Symbol	Parameter Conditions		Min.	Тур.	Max.	Unit	
BV <sub>DSS</sub>	Drain-Source Breakdown Voltage	V <sub>GS</sub> =0V , I <sub>D</sub> =250uA	30			V	
Ъ	0, 1, 5, 1, 0, 0, 5, 1, 2	V <sub>GS</sub> =10V , I <sub>D</sub> =20A		4.4	5.8	mΩ	
R <sub>DS(ON)</sub>	Static Drain-Source On-Resistance <sup>2</sup>	V <sub>GS</sub> =4.5V , I <sub>D</sub> =15A		6.9	9		
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>GS</sub> =V <sub>DS</sub> , I <sub>D</sub> =250uA	1.2		2.5	V	
1	Drain-Source Leakage Current	V <sub>DS</sub> =24V , V <sub>GS</sub> =0V , T <sub>J</sub> =25°C			1	uA	
I <sub>DSS</sub>		V <sub>DS</sub> =24V , V <sub>GS</sub> =0V , T <sub>J</sub> =55°C			5		
Igss	Gate-Source Leakage Current	V <sub>GS</sub> =±20V , V <sub>DS</sub> =0V			±100	nA	
gfs	Forward Transconductance	V <sub>DS</sub> =5V , I <sub>D</sub> =20A		67		S	
Rg	Gate Resistance	V <sub>DS</sub> =0V , V <sub>GS</sub> =0V , f=1MHz		1.7		Ω	
Qg	Total Gate Charge (4.5V)			8			
Qgs	Gate-Source Charge	V <sub>DS</sub> =15V , V <sub>GS</sub> =4.5V , I <sub>D</sub> =15A		2.4		nC	
Q <sub>gd</sub>	Gate-Drain Charge			3.2			
T <sub>d(on)</sub>	Turn-On Delay Time			7.1			
Tr	Rise Time	$V_{DD}$ =15V , $V_{GS}$ =10V , $R_{G}$ =3.3 $\Omega$		40		ns	
T <sub>d(off)</sub>	Turn-Off Delay Time	I <sub>D</sub> =15A		15			
$T_f$	Fall Time			6			
Ciss	Input Capacitance			814			
$C_{oss}$	Output Capacitance	V <sub>DS</sub> =15V , V <sub>GS</sub> =0V , f=1MHz		498		pF	
Crss	Reverse Transfer Capacitance			41			
Is	Continuous Source Current <sup>1,6</sup>	V <sub>G</sub> =V <sub>D</sub> =0V , Force Current			60	Α	
$V_{\text{SD}}$	Diode Forward Voltage <sup>2</sup>	V <sub>GS</sub> =0V , I <sub>S</sub> =1A , T <sub>J</sub> =25°C			1	V	
t <sub>rr</sub>	Reverse Recovery Time	IF=20A , di/dt=100A/μs ,		15		nS	
Qrr	Reverse Recovery Charge	T <sub>J</sub> =25℃		25		nC	

#### Note:

- 1. The data tested by surface mounted on a 1 inch<sup>2</sup> FR-4 board with 2OZ copper.
- 2.The data tested by pulsed , pulse width  $\leqq$  300us , duty cycle  $\leqq$  2%
- 3. The EAS data shows Max. rating . The test condition is  $V_{DD}$ =25V,  $V_{GS}$ =10V, L=0.1mH,  $I_{AS}$ =24A
- 4. The power dissipation is limited by  $150^{\circ}\text{C}$  junction temperature 5. The data is theoretically the same as  $I_D$  and  $I_{DM}$ , in real applications, should be limited by total power dissipation.



# **Typical Characteristics**

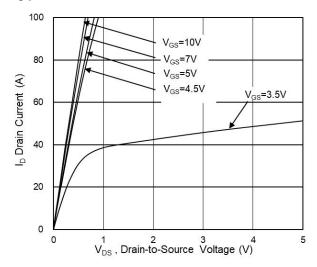


Fig.1 Typical Output Characteristics

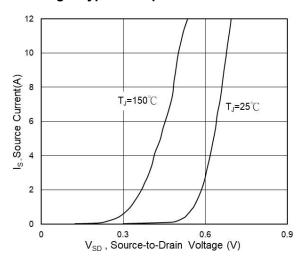


Fig.3 Source Drain Forward Characteristics

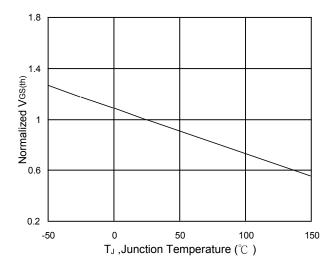


Fig.5 Normalized V<sub>GS(th)</sub> vs T<sub>J</sub>

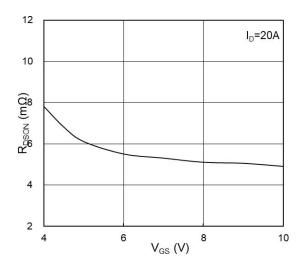


Fig.2 On-Resistance vs G-S Voltage

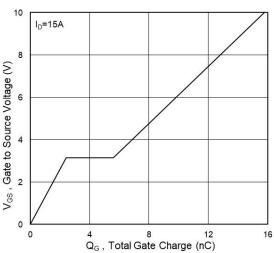


Fig.4 Gate-Charge Characteristics

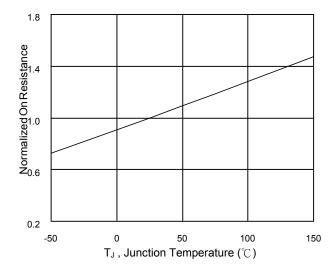
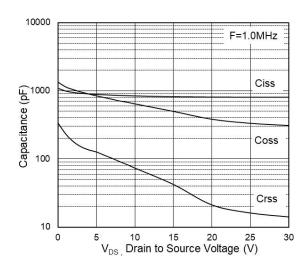


Fig.6 Normalized R<sub>DSON</sub> vs T<sub>J</sub>



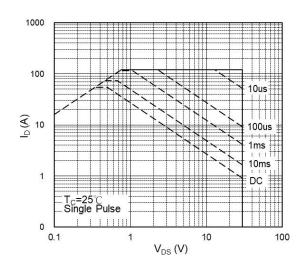


Fig.7 Capacitance

Fig.8 Safe Operating Area

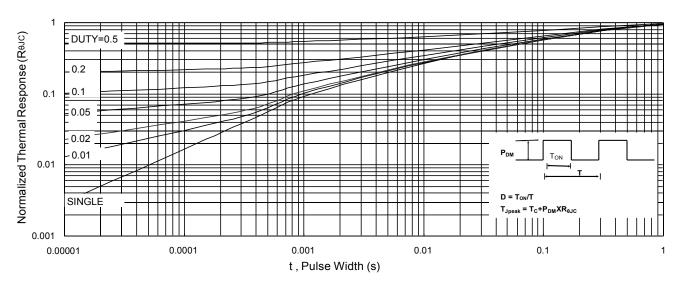


Fig.9 Normalized Maximum Transient Thermal Impedance

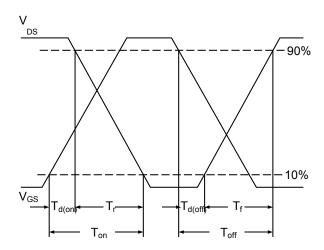


Fig.10 Switching Time Waveform

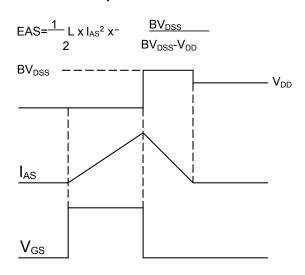
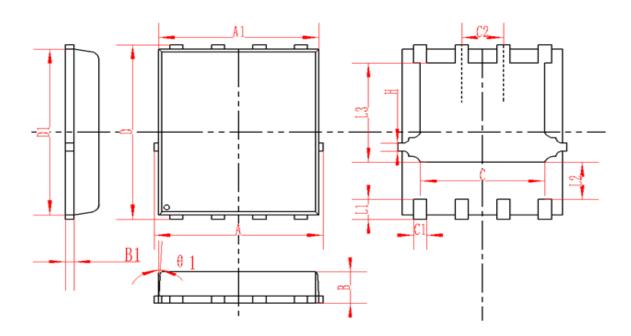


Fig.11 Unclamped Inductive Switching Waveform



# **DFN5X6-8L Package Information**



SYMBOL		MM		INCH			
STIVIDOL	MIN	NOM	MAX	MIN	NOM	MAX	
А	4.95	5	5.05	0.195	0.197	0.199	
A1	4.82	4.9	4.98	0.190	0.193	0.196	
D	5.98	6	6.02	0.235	0.236	0.237	
D1	5.67	5.75	5.83	0.223	0.226	0.230	
В	0.9	0.95	1	0.035	0.037	0.039	
B1	0.254REF		0.010REF				
С	3.95	4	4.05	0.156	0.157	0.159	
C1	0.35	0.4	0.45	0.014	0.016	0.018	
C2		1.27TYP			0.5TYP		
θ1	8°	10°	12°	8°	10°	12°	
L1	0.63	0.64	0.65	0.025	0.025	0.026	
L2	1.2	1.3	1.4	0.047	0.051	0.055	
L3	3.415	3.42	3.425	0.134	0.135	0.135	
Η	0.24	0.25	0.26	0.009	0.010	0.010	



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